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Kind regards,

Team Nexperia



PHPT610035PK

PNP/PNP matched high power double bipolar transistor

24 October 2014

Product data sheet

1. General description

PNP/PNP high power matched double bipolar transistor in a SOT1205 (LFAK56D) Surface-Mounted Device (SMD) power plastic package. Matched version of PHPT610030PK.

NPN/NPN complement: PHPT610035NK.

2. Features and benefits

- Current gain matching 10 %
- High thermal power dissipation capability
- Suitable for high temperature applications up to 175 °C
- Reduced Printed-Circuit Board (PCB) requirements comparing to transistors in DPAK
- High energy efficiency due to less heat generation
- AEC-Q101 qualified

3. Applications

- Current mirror
- Motor control
- Power management
- Backlighting applications
- Relay replacement
- Differential amplifiers

4. Quick reference data

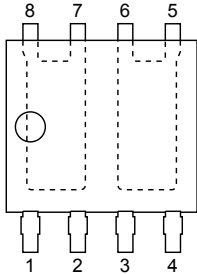
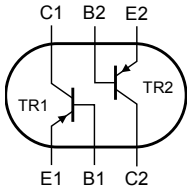
Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Per transistor						
V_{CEO}	collector-emitter voltage	open base	-	-	-100	V
I_C	collector current		-	-	-3	A
Per transistor						
R_{CEsat}	collector-emitter saturation resistance	$I_C = -2\text{ A}; I_B = -200\text{ mA};$ pulsed; $t_p \leq 300\ \mu\text{s}; \delta \leq 0.02; T_{amb} = 25\text{ °C}$	-	110	180	m Ω



5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	E1	emitter TR1	 <p>LFPAK56D (SOT1205)</p>	 <p><i>sym138</i></p>
2	B1	base TR1		
3	E2	emitter TR2		
4	B2	base TR2		
5	C2	collector TR2		
6	C2	collector TR2		
7	C1	collector TR1		
8	C1	collector TR1		

6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PHPT610035PK	LFPAK56D	Plastic single ended surface mounted package (LFPAK56D); 8 leads	SOT1205

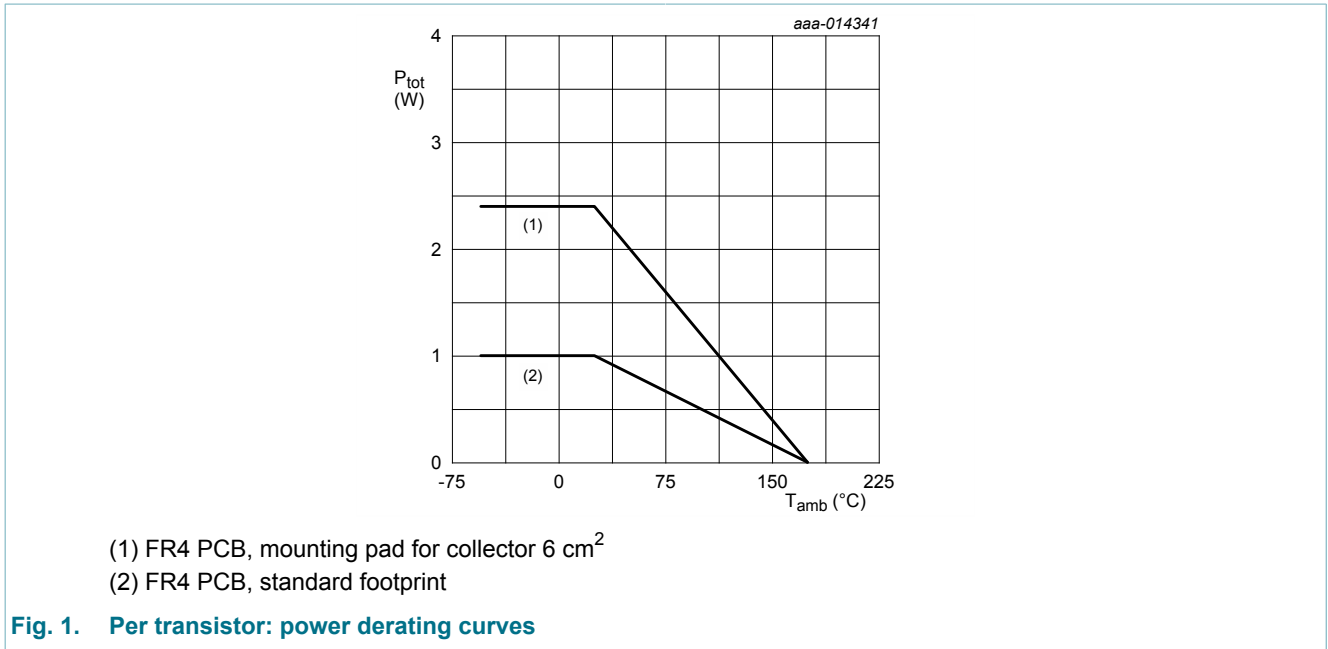
7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
Per transistor						
V _{CBO}	collector-base voltage	open emitter		-	-100	V
V _{CEO}	collector-emitter voltage	open base		-	-100	V
V _{EBO}	emitter-base voltage	open collector		-	-8	V
I _C	collector current			-	-3	A
I _{CM}	peak collector current	single pulse; t _p ≤ 1 ms		-	-8	A
I _B	base current			-	-0.5	A
P _{tot}	total power dissipation	T _{amb} ≤ 25 °C	[1]	-	1	W
			[2]	-	2.4	W
			[3]	-	25	W
Per device						
P _{tot}	total power dissipation	T _{amb} ≤ 25 °C	[1]	-	1.25	W
			[2]	-	3	W
			[4]	-	5	W
T _j	junction temperature			-	175	°C
T _{amb}	ambient temperature			-55	175	°C
T _{stg}	storage temperature			-65	175	°C

- [1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for collector 6 cm².
- [3] Power dissipation from junction to mounting base.
- [4] Device mounted on a ceramic PCB, Al₂O₃, standard footprint.

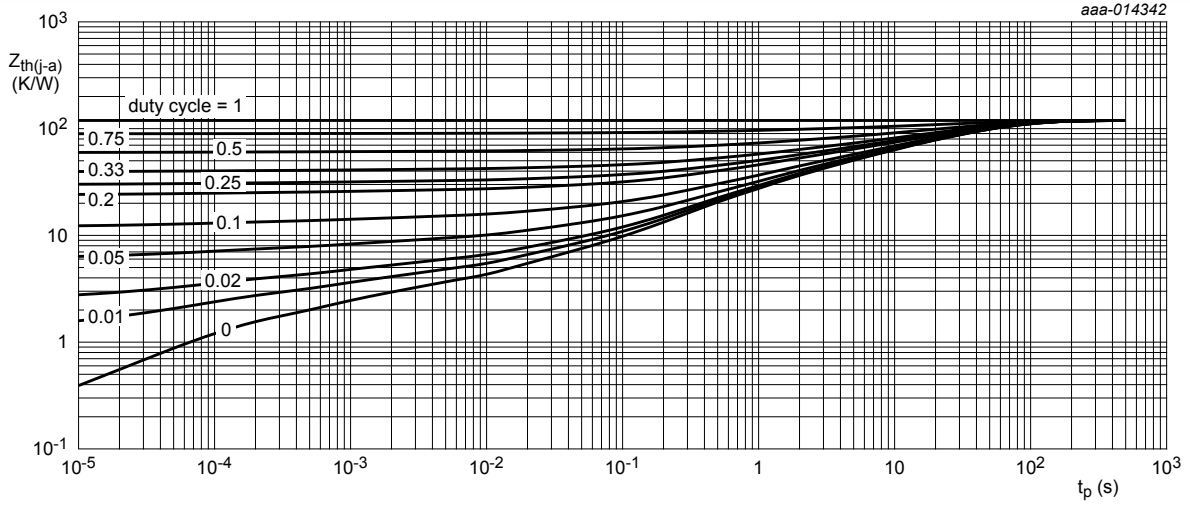


8. Thermal characteristics

Table 5. Thermal characteristics

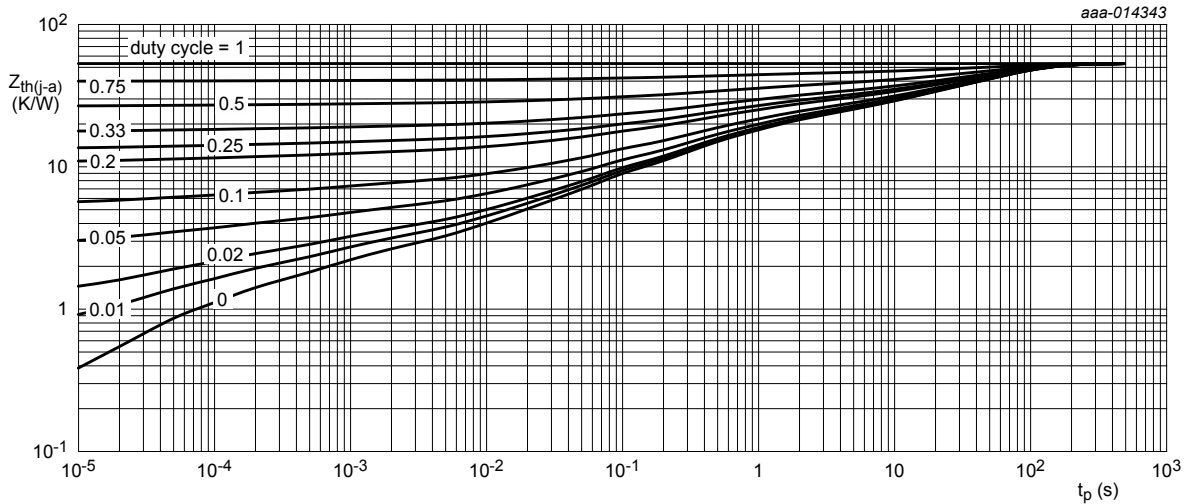
Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Per transistor							
R _{th(j-a)}	thermal resistance from junction to ambient	in free air	[1]	-	-	150	K/W
			[2]	-	-	62.5	K/W
R _{th(j-sp)}	thermal resistance from junction to solder point			-	-	6	K/W
Per device							
R _{th(j-a)}	thermal resistance from junction to ambient	in free air	[1]	-	-	120	K/W
			[2]	-	-	50	K/W
			[3]	-	-	30	K/W

- [1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for collector 6 cm².
- [3] Device mounted on a ceramic PCB, Al₂O₃, standard footprint.



FR4 PCB, standard footprint

Fig. 2. Per transistor: transient thermal impedance from junction to ambient as a function of pulse duration; typical values



FR4 PCB, mounting pad for collector 6 cm^2

Fig. 3. Per transistor: transient thermal impedance from junction to ambient as a function of pulse duration; typical values

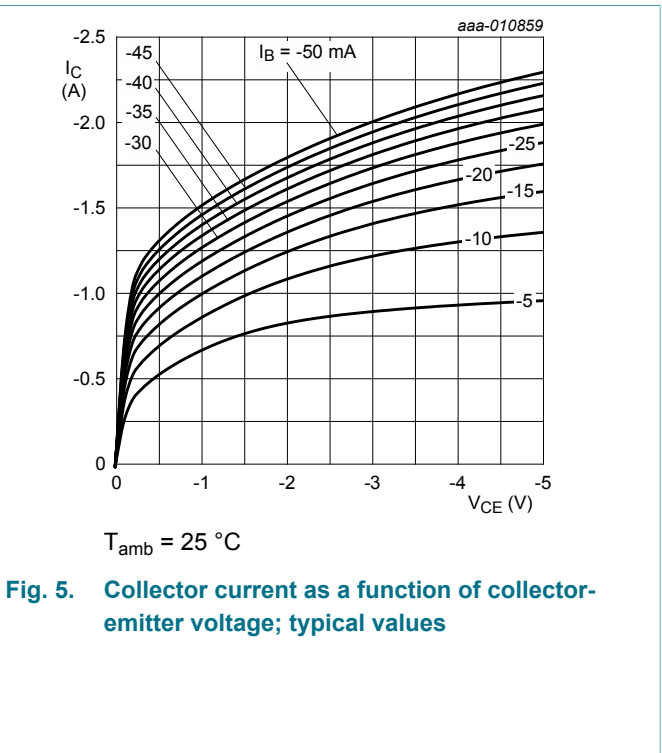
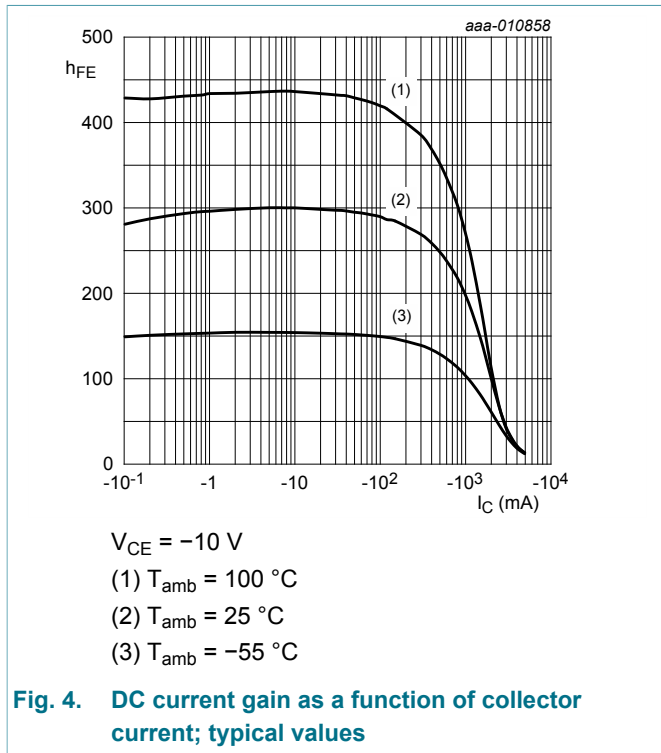
9. Characteristics

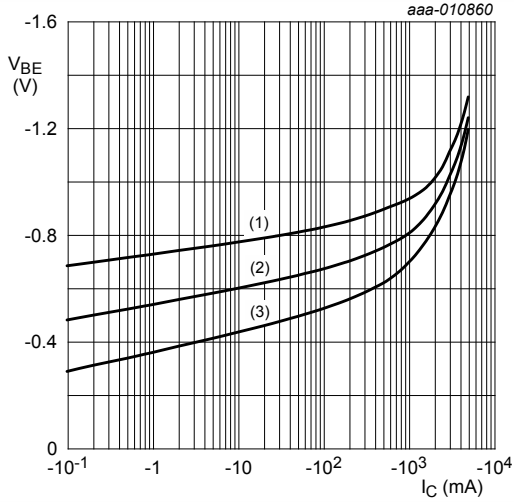
Table 6. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
h_{FE1}/h_{FE2}	h_{FE} matching	$V_{CE} = -2\text{ V}; I_C = 1\text{ A}$	0.9	1	1.1	
Per transistor						
I_{CBO}	collector-base cut-off current	$V_{CB} = -80\text{ V}; I_E = 0\text{ A}; T_{amb} = 25\text{ }^\circ\text{C}$	-	-	-100	nA
		$V_{CB} = -80\text{ V}; I_E = 0\text{ A}; T_j = 150\text{ }^\circ\text{C}$	-	-	-50	μA
I_{CES}	collector-emitter cut-off current	$V_{CE} = -80\text{ V}; V_{BE} = 0\text{ V}; T_{amb} = 25\text{ }^\circ\text{C}$	-	-	-100	nA
I_{EBO}	emitter-base cut-off current	$V_{EB} = -7\text{ V}; I_C = 0\text{ A}; T_{amb} = 25\text{ }^\circ\text{C}$	-	-	-100	nA
h_{FE}	DC current gain	$V_{CE} = -10\text{ V}; I_C = -500\text{ mA}; T_{amb} = 25\text{ }^\circ\text{C}$	150	220	-	
		$V_{CE} = -10\text{ V}; I_C = -1\text{ A};$ pulsed; $t_p \leq 300\text{ }\mu\text{s}; \delta \leq 0.02; T_{amb} = 25\text{ }^\circ\text{C}$	80	210	-	
		$V_{CE} = -10\text{ V}; I_C = -2\text{ A};$ pulsed; $t_p \leq 300\text{ }\mu\text{s}; \delta \leq 0.02; T_{amb} = 25\text{ }^\circ\text{C}$	20	100	-	
		$V_{CE} = -2\text{ V}; I_C = -1\text{ A}; T_{amb} = 25\text{ }^\circ\text{C}$	100	200	-	
		$V_{CE} = -10\text{ V}; I_C = -3\text{ A};$ pulsed; $t_p \leq 300\text{ }\mu\text{s}; \delta \leq 0.02; T_{amb} = 25\text{ }^\circ\text{C}$	10	40	-	
V_{CEsat}	collector-emitter saturation voltage	$I_C = -500\text{ mA}; I_B = -50\text{ mA}; T_{amb} = 25\text{ }^\circ\text{C}$	-	-70	-110	mV
		$I_C = -2\text{ A}; I_B = -200\text{ mA};$ pulsed; $t_p \leq 300\text{ }\mu\text{s}; \delta \leq 0.02; T_{amb} = 25\text{ }^\circ\text{C}$	-	-220	-360	mV
R_{CEsat}	collector-emitter saturation resistance	$t_p \leq 300\text{ }\mu\text{s}; \delta \leq 0.02; T_{amb} = 25\text{ }^\circ\text{C}$	-	110	180	$\text{m}\Omega$
V_{BEsat}	base-emitter saturation voltage	$I_C = -1\text{ A}; I_B = -50\text{ mA};$ pulsed; $t_p \leq 300\text{ }\mu\text{s}; \delta \leq 0.02; T_{amb} = 25\text{ }^\circ\text{C}$	-	-0.91	-1	V
		$I_C = -2\text{ A}; I_B = -200\text{ mA};$ pulsed; $t_p \leq 300\text{ }\mu\text{s}; \delta \leq 0.02; T_{amb} = 25\text{ }^\circ\text{C}$	-	-1.02	-1.2	V
V_{BEon}	base-emitter turn-on voltage	$V_{CE} = -2\text{ V}; I_C = -100\text{ mA};$ pulsed; $t_p \leq 300\text{ }\mu\text{s}; \delta \leq 0.02; T_{amb} = 25\text{ }^\circ\text{C}$	-	-0.68	-0.9	V
t_d	delay time	$V_{CC} = -12.5\text{ V}; I_C = -1\text{ A}; I_{Bon} = -50\text{ mA}; I_{Boff} = 50\text{ mA}; T_{amb} = 25\text{ }^\circ\text{C}$	-	20	-	ns
t_r	rise time		-	180	-	ns
t_{on}	turn-on time		-	200	-	ns
t_s	storage time		-	350	-	ns
t_f	fall time		-	220	-	ns
t_{off}	turn-off time		-	570	-	ns

PNP/PNP matched high power double bipolar transistor

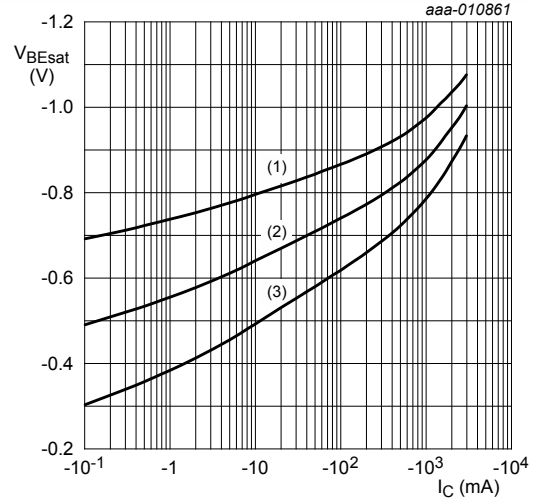
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
f_T	transition frequency	$V_{CE} = -10\text{ V}$; $I_C = -100\text{ mA}$; $f = 100\text{ MHz}$; $T_{amb} = 25\text{ }^\circ\text{C}$	-	125	-	MHz
C_c	collector capacitance	$V_{CB} = -10\text{ V}$; $I_E = 0\text{ A}$; $i_e = 0\text{ A}$; $f = 1\text{ MHz}$; $T_{amb} = 25\text{ }^\circ\text{C}$	-	30	-	pF





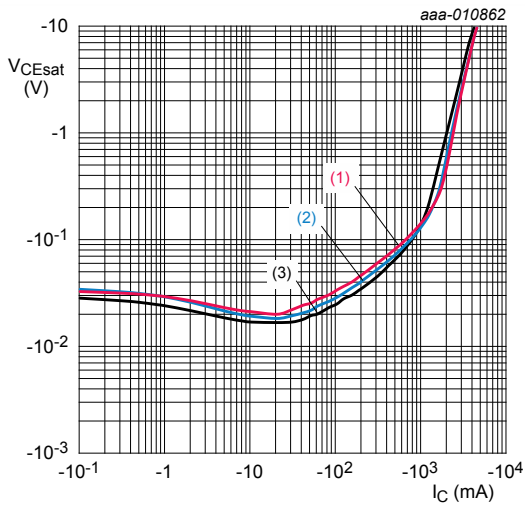
$V_{CE} = -2 \text{ V}$
 (1) $T_{amb} = -55 \text{ }^\circ\text{C}$
 (2) $T_{amb} = 25 \text{ }^\circ\text{C}$
 (3) $T_{amb} = 100 \text{ }^\circ\text{C}$

Fig. 6. Base-emitter voltage as a function of collector current; typical values



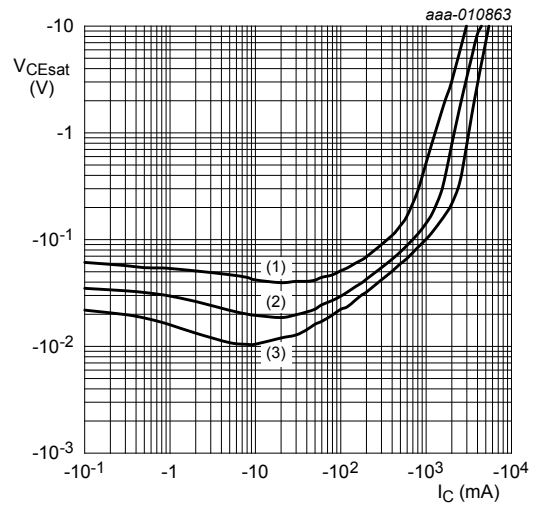
$I_C/I_B = 20$
 (1) $T_{amb} = -55 \text{ }^\circ\text{C}$
 (2) $T_{amb} = 25 \text{ }^\circ\text{C}$
 (3) $T_{amb} = 100 \text{ }^\circ\text{C}$

Fig. 7. Base-emitter saturation voltage as a function of collector current; typical values



$I_C/I_B = 20$
 (1) $T_{amb} = 100 \text{ }^\circ\text{C}$
 (2) $T_{amb} = 25 \text{ }^\circ\text{C}$
 (3) $T_{amb} = -55 \text{ }^\circ\text{C}$

Fig. 8. Collector-emitter saturation voltage as a function of collector current; typical values



$T_{amb} = 25 \text{ }^\circ\text{C}$
 (1) $I_C/I_B = 50$
 (2) $I_C/I_B = 20$
 (3) $I_C/I_B = 10$

Fig. 9. Collector-emitter saturation voltage as a function of collector current; typical values

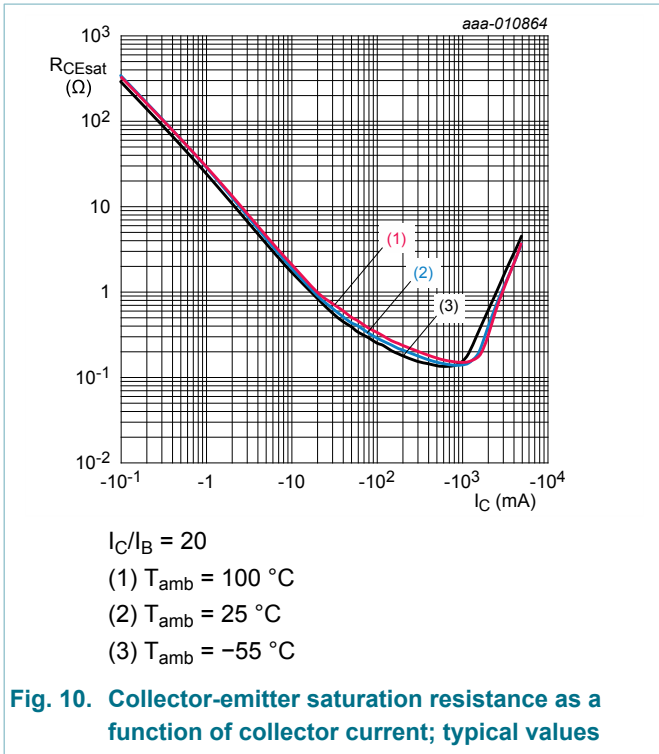


Fig. 10. Collector-emitter saturation resistance as a function of collector current; typical values

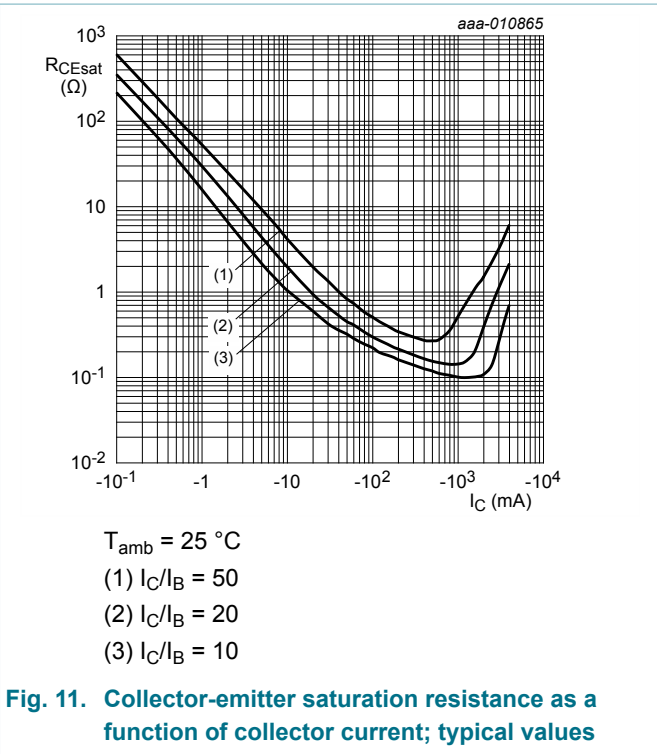


Fig. 11. Collector-emitter saturation resistance as a function of collector current; typical values

10. Test information

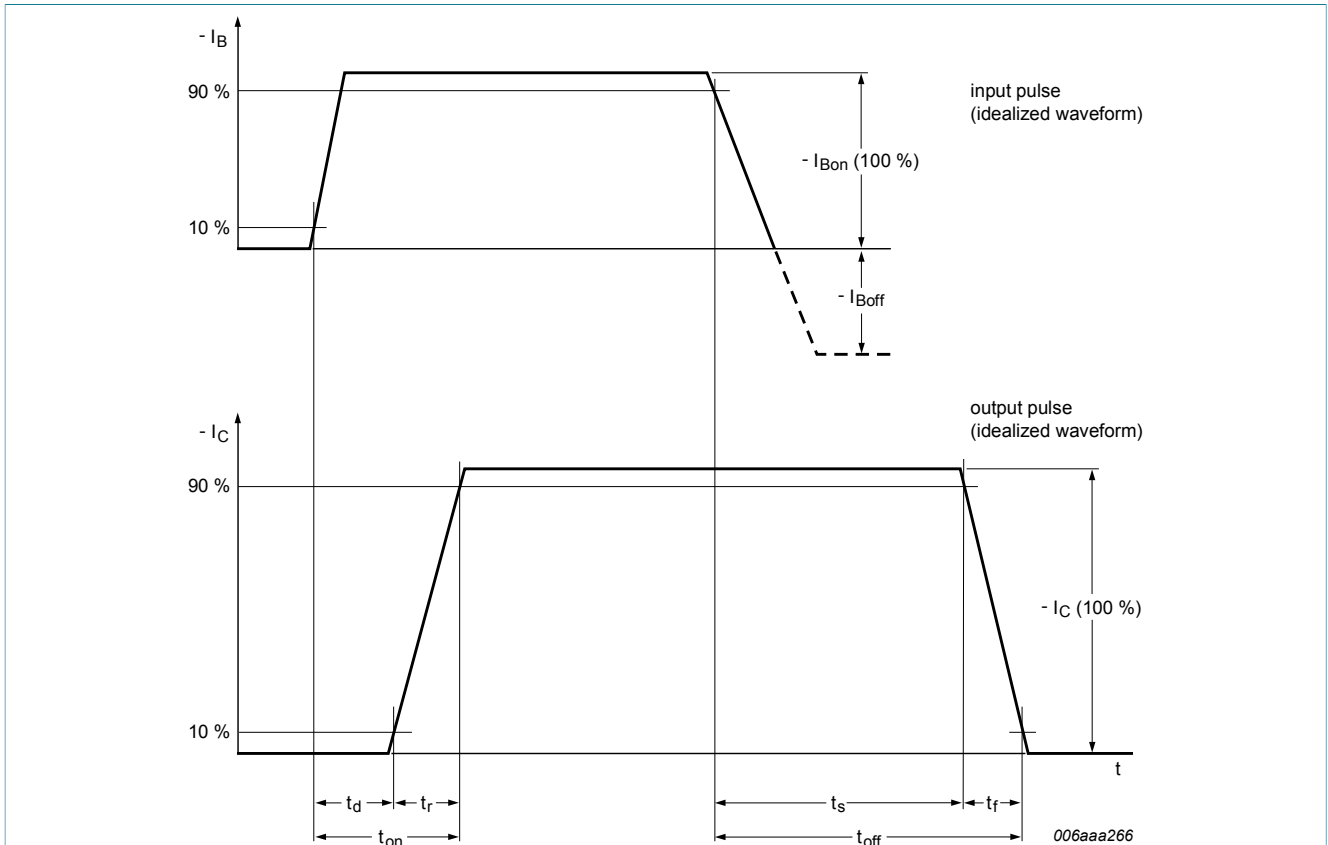


Fig. 12. BISS transistor switching time definition

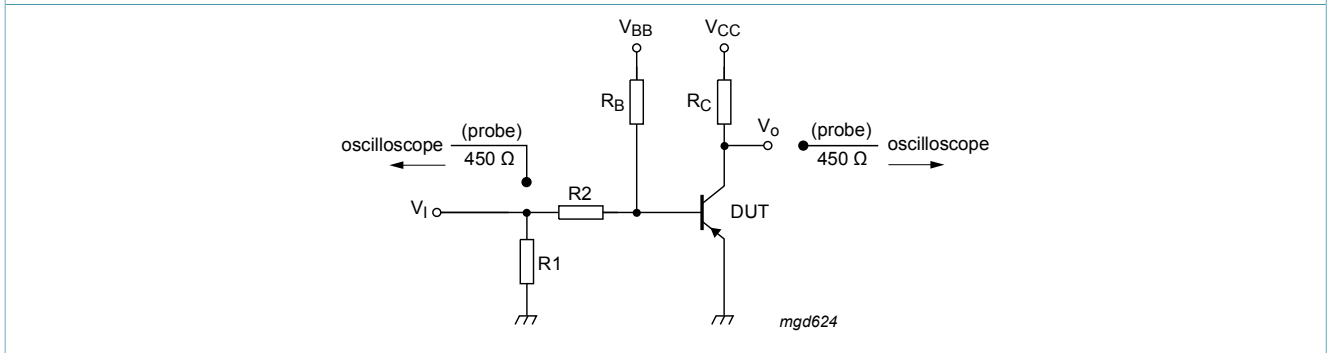


Fig. 13. Test circuit for switching times

10.1 Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - *Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

11. Package outline

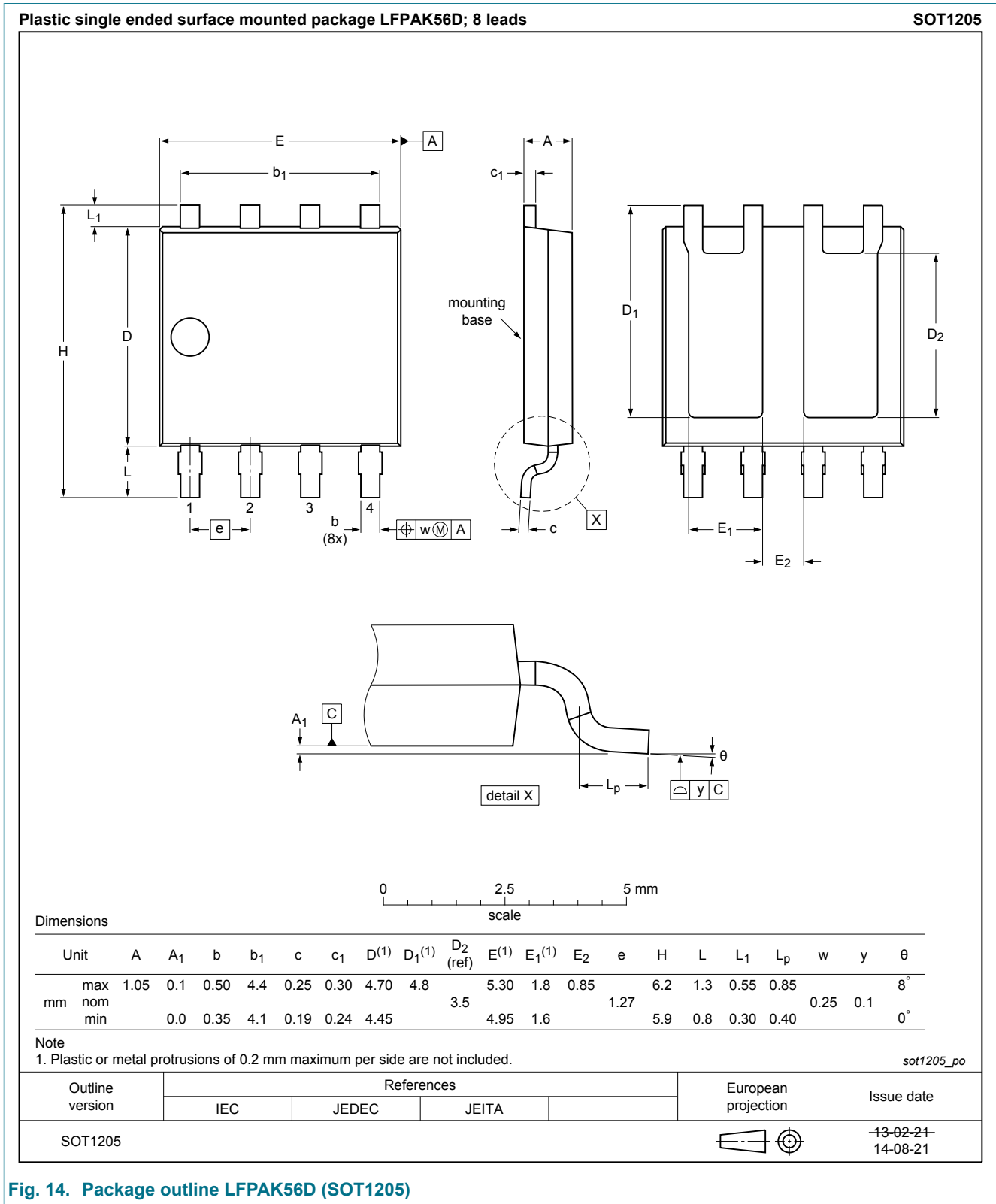


Fig. 14. Package outline LFAK56D (SOT1205)

12. Soldering

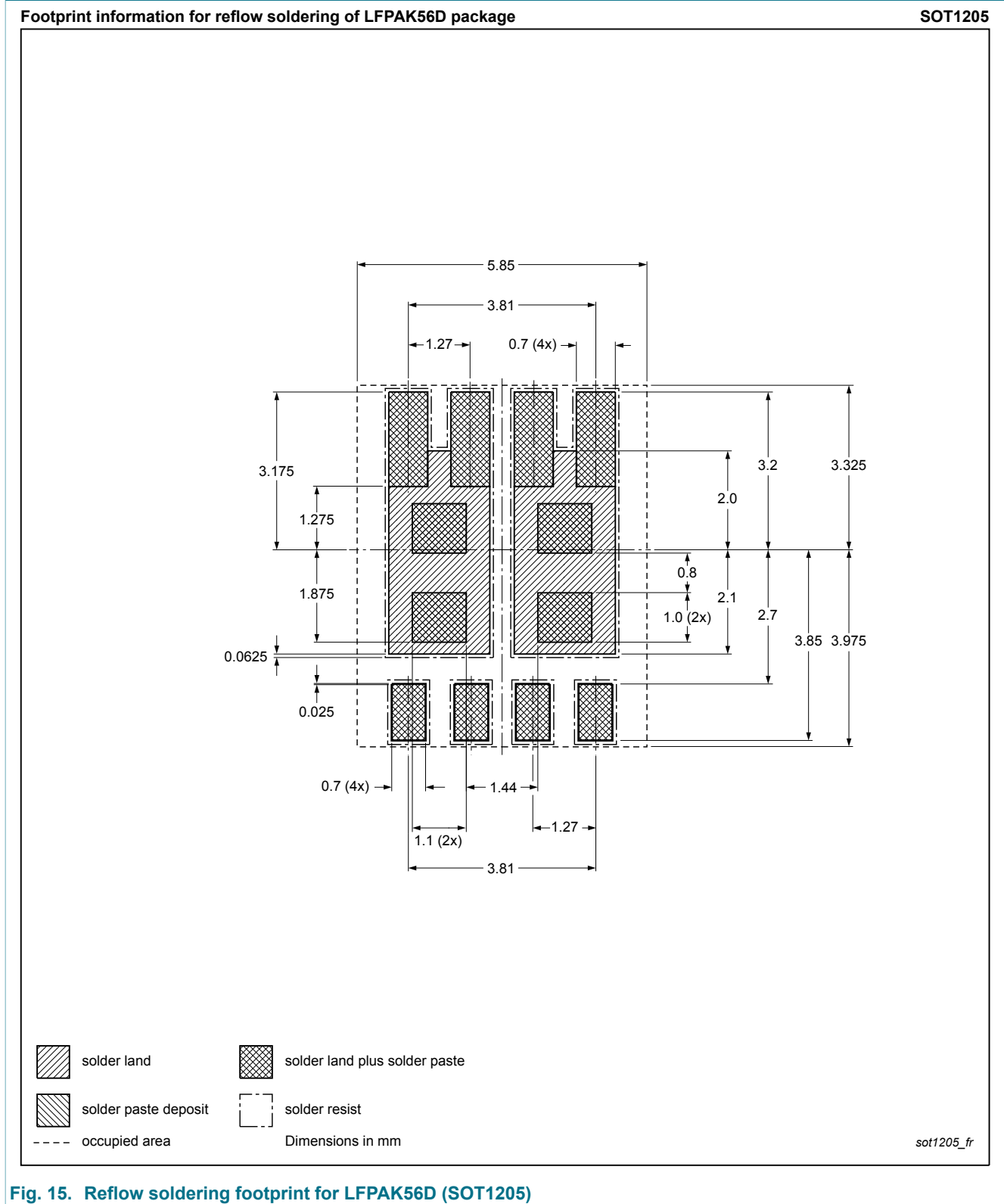


Fig. 15. Reflow soldering footprint for LFPAK56D (SOT1205)

13. Revision history

Table 7. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
PHPT610035PK v.1	20141024	Product data sheet	-	-

14. Legal information

14.1 Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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15. Contents

1	General description	1
2	Features and benefits	1
3	Applications	1
4	Quick reference data	1
5	Pinning information	2
6	Ordering information	2
7	Limiting values	3
8	Thermal characteristics	4
9	Characteristics	6
10	Test information	10
10.1	Quality information	10
11	Package outline	11
12	Soldering	12
13	Revision history	13
14	Legal information	14
14.1	Data sheet status	14
14.2	Definitions	14
14.3	Disclaimers	14
14.4	Trademarks	15

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